



Product Change Notification / KSRA-19GIRS482

Date:

25-Feb-2018

Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers, 8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 2923 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 200K wafer technology available in 28L QFN package at NSEB assembly site

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 200K wafer technology available in 28L QFN package at NSEB assembly site

Pre Change: Using gold (Au) bond wire, 8200T and 8600 die attach and G770HCD and G700LTD mold compound material.

Post Change:Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	UTAC Thai Limited LTD. (NSEB)		UTAC Thai Limited LTD. (NSEB)
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	EFTEC-64T		EFTEC-64T

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:March 25, 2018 (date code: 1813)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

Workweek	April 2017					-	February 2018				March 2018					
	13	14	15	16	17		-	>	05	06	07	08	10	11	12	13
Initial PCN Issue Date					X											
Qual Report Availability																
Final PCN Issue Date																
Estimated Implementation Date																X

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History: April 27, 2017: Issued initial notification.

February 25, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on March 25, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_KSRA-19GIRS482_Affected CPN.pdf](#)

[PCN_KSRA-19GIRS482_Affected CPN.xlsx](#)

[PCN_KSRA-19GIRS482_Qual Report.pdf](#)

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